PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

| SUBMISSION TYPE: | NEW ASSIGNMENT |
|-----------------------|----------------|
| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|--------------------|----------------|
| Hirotoshi Ichikawa | 11/26/2007 |
| Fusao Ishii | 11/25/2007 |

RECEIVING PARTY DATA

| Name: | Silicon Quest Kabushiki-Kaisha | |
|-----------------|--------------------------------|--|
| Street Address: | 1588-128 Koshigoe Kamakura-Shi | |
| City: | Kanagawa-Ken, 248-0033 | |
| State/Country: | JAPAN | |

| Name: | Olympus Corporation | |
|-----------------|--|--|
| Street Address: | Shinjukumonolith, 3-1 Nishi-Shinjuku 2-chome | |
| City: | Shinjuku-ku, Tokyo 163-0914 | |
| State/Country: | JAPAN | |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 12004598 |

CORRESPONDENCE DATA

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| ATTORNEY DOCKET NUMBER: | SQ-0626 |
|-------------------------|-----------|
| NAME OF SUBMITTER: | Bo-In Lin |

PATENT REEL: 021263 FRAME: 0525

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Total Attachments: 2 source=assignment#page1.tif

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PATENT REEL: 021263 FRAME: 0526

ASSIGNMENT

INVENTOR

Whereas, I, Hirotoshi Ichikawa of

AND CITY

8-10 Takakura-machi, Hachioji-shi, Tokyo 192-0033, Japan

have invented:

TITLE

MICROMIRROR MANUFACTURING METHOD

and executed a United States patent application therefor

DATE INVENTOR SIGNED THE DECLARATION on Nov. 26, 2007

Whereas, **Olympus Corporation** having a place of business at **Tokyo**, Japan, (hereinafter called **Olympus**), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to **Olympus**, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to **Olympus** its successors and assigns; and I hereby agree that **Olympus** may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND DATE

Signed and Sealed at Tokyo, Japan

on Nov. 26, 2007

Odvaloshi Shihara SIGNATURE OF INVENTOR

PATENT REEL: 021263 FRAME: 0527

Docket No. 50-062 6

ASSIGNMENT

Whereas, I,

Fusao Ishii

of

INVENTOR AND CITY

350 Sharon Park Drive G26 Menlo Park, California 94025

have invented:

TITLE

MICROMIRROR MANUFACTURING METHOD

and executed a United States patent application therefor on 25,200

DATE

INVENTOR SIGNED THE DECLARATION

Whereas, Silicon Quest Kabushiki-Kaisha having a place of business at Kamakura, Japan, (hereinafter called Silicon Quest), desires to acquire the entire right, title and interest of said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I, the above named, hereby sell, assign, and transfer to **Silicon Quest**, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing said United States application, and I request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to **Silicon Quest** its successors and assigns; and I hereby agree that **Silicon Quest** may apply for foreign Letters Patent on said invention and I will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by

CITY AND

Signed and Sealed at California, USA on Nov. 25, 2007

SIGNATURE OF INVENTOR

PATENT REEL: 021263 FRAME: 0528

RECORDED: 07/21/2008